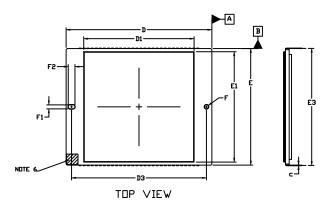
CERAMIC DIP 60, 63.8x51

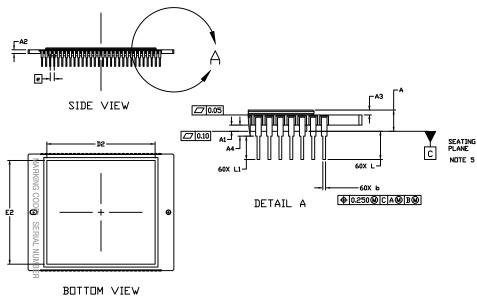
CASE 125BR ISSUE O

DATE 06 JUL 2016



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
- 4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
- 5. THE SEATING PLANE IS DEFINED BY THE DUTER HEATSINK SURFACE.
- PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.



MILLIMETERS		
MIN.	MAX.	
	3.67	
0.95	1.05	
1.48 1.82		
0.80 REF		
1.53	2.03	
0.38	0.54	
0.20	0.30	
63.16	64.44	
48.18	48.34	
47.27	47.53	
58.41	59.59	
50.49	51.51	
48.18	48.34	
45.27	45.53	
50.87 51.63		
1.778 BSC		
1.60	1.90	
1.60	1.90	
2.80	3.10	
4.32	4.82	
3.54	4.04	
	MIN 0.95 1.48 0.80 1.53 0.38 0.20 63.16 48.18 47.27 58.41 50.49 48.18 45.27 1.778 1.60 1.60 2.80 4.32	

DOCUMENT NUMBER:	98AON13106G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	: CERAMIC DIP 60, 63.8x51		PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.